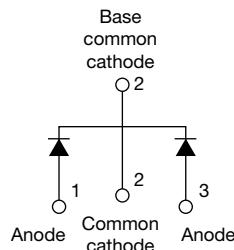


Hyperfast Rectifier, 2 x 4 AFRED Pt®


DPAK (TO-252AA)


FEATURES

- Hyperfast recovery time
- 175 °C max. operating junction temperature
- Output rectification freewheeling
- Low forward voltage drop reduced Q_{rr} and soft recovery
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

PRIMARY CHARACTERISTICS	
I _{F(AV)}	2 x 4 A
V _R	200 V
V _F at I _F	0.71 V
t _{rr} (typ.)	23 ns
T _J max.	175 °C
Package	DPAK (TO-252AA)
Circuit configuration	Common cathode

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V _{RRM}		200	V
Average rectified forward current	I _{F(AV)}	T _C = 164 °C	8	A
Non-repetitive peak surge current per leg	I _{FSM}	T _J = 25 °C	80	
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 µA	200	-	-	V
Forward voltage per leg	V _F	I _F = 4 A	-	0.87	0.95	
		I _F = 8 A	-	0.95	1.10	
		I _F = 4 A, T _J = 150 °C	-	0.71	0.80	
		I _F = 8 A, T _J = 150 °C	-	0.8	1.0	
Reverse leakage current per leg	I _R	V _R = V _R rated	-	-	4	µA
		T _J = 125 °C, V _R = V _R rated	-	-	40	
		T _J = 150 °C, V _R = V _R rated	-	-	80	
Junction capacitance per leg	C _T	V _R = 200 V	-	17	-	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1 \text{ A}$, $dI_F/dt = 100 \text{ A}/\mu\text{s}$, $V_R = 30 \text{ V}$		-	23	27	ns
		$T_J = 25^\circ\text{C}$		-	20	-	
		$T_J = 125^\circ\text{C}$		-	27	-	
Peak recovery current	I_{RRM}	$T_J = 25^\circ\text{C}$	$I_F = 4 \text{ A}$, $dI_F/dt = 200 \text{ A}/\mu\text{s}$, $V_R = 160 \text{ V}$	-	2	-	A
		$T_J = 125^\circ\text{C}$		-	3.4	-	
		$T_J = 25^\circ\text{C}$		-	20	-	
Reverse recovery charge	Q_{rr}	$T_J = 125^\circ\text{C}$		-	46	-	nC

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}			-65	-	175	°C
Thermal resistance, junction to case per leg per device	R_{thJC}			-	2.7	3.2	°C/W
				-	1.35	1.6	
Approximate weight				0.3		g	
				0.01		oz.	
Marking device		Case style DPAK (TO-252AA)		8CWH02FN			

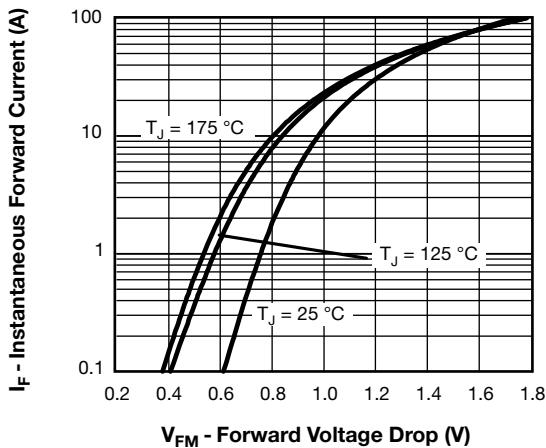


Fig. 1 - Typical Forward Voltage Drop Characteristics

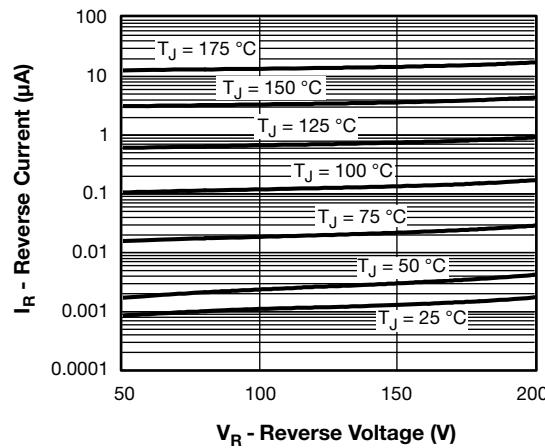


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

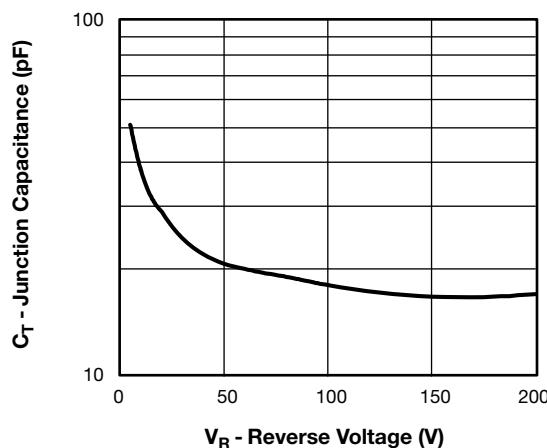


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

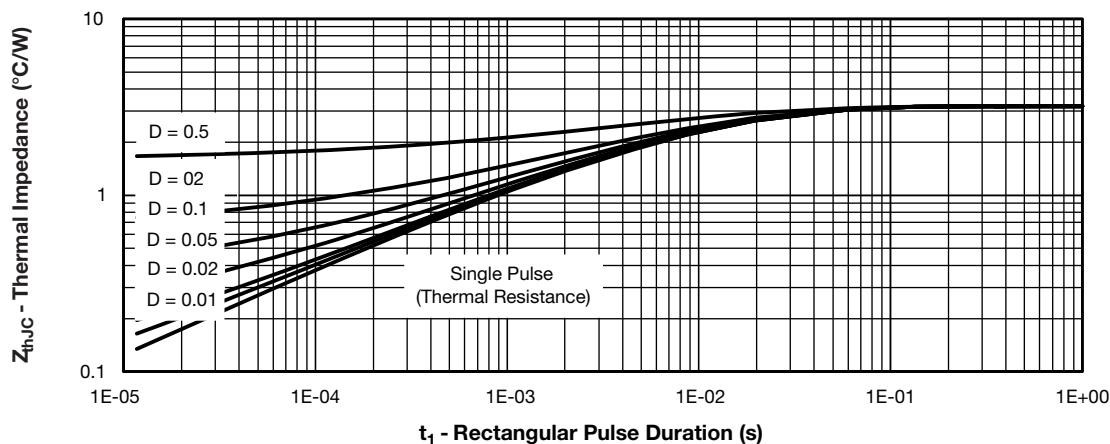


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

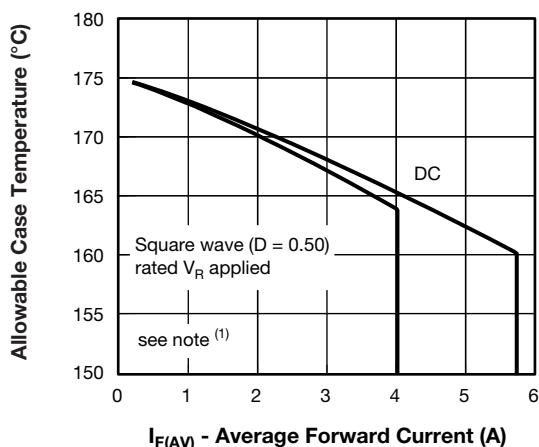


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

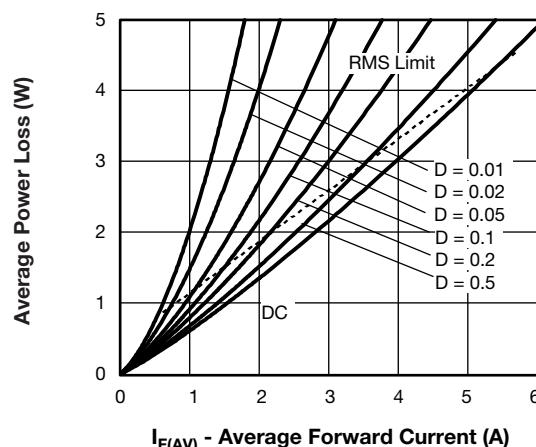


Fig. 6 - Forward Power Loss Characteristics

Note

(1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

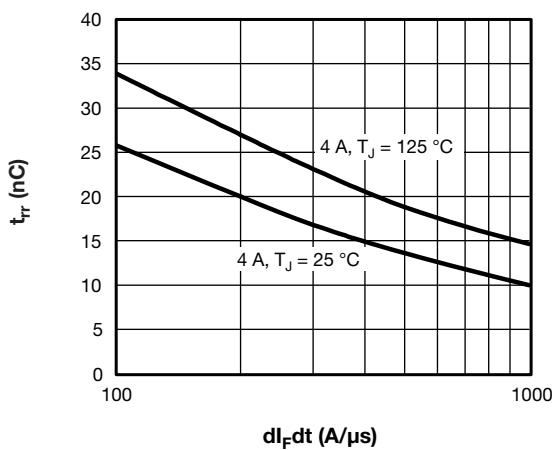


Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

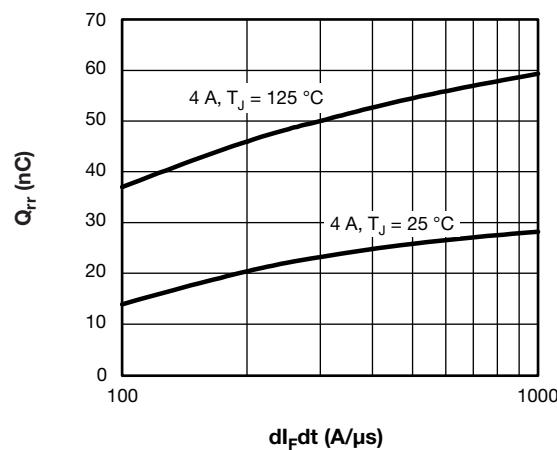


Fig. 8 - Typical Stored Charge vs. di_F/dt

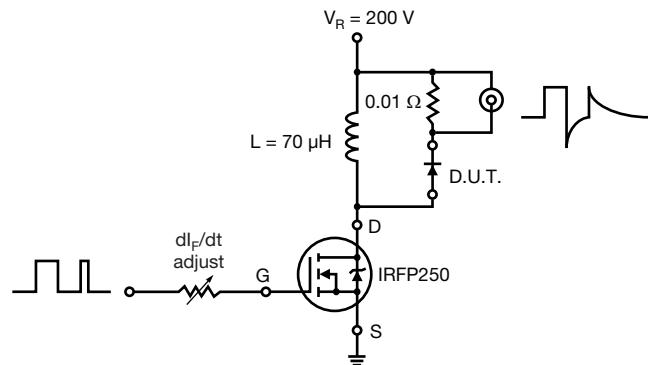


Fig. 9 - Reverse Recovery Parameter Test Circuit

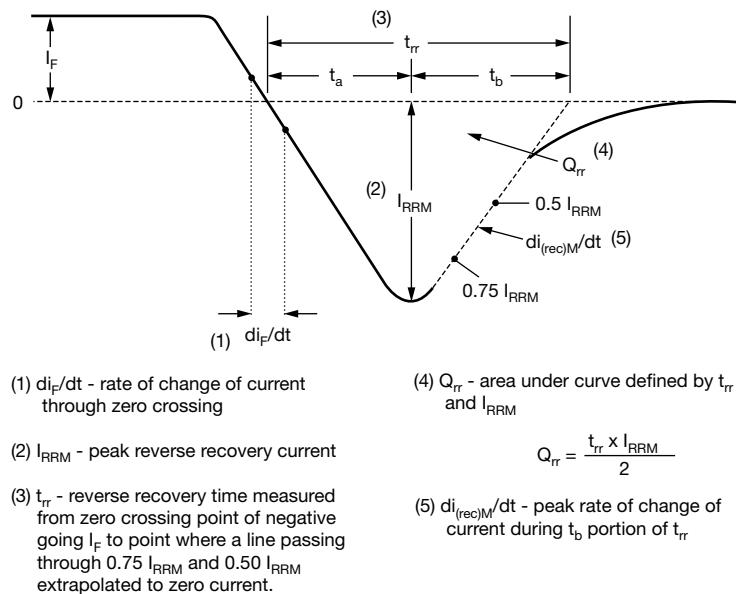


Fig. 10 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	VS-	8	C	W	H	02	FN	TRL	-M3
	1	2	3	4	5	6	7	8	9

- 1** - Vishay Semiconductors product
- 2** - Current rating (8 = 8 A)
- 3** - Circuit configuration:
C = common cathode
- 4** - Package identifier:
W = D-PAK
- 5** - H = hyperfast recovery
- 6** - Voltage rating (02 = 200 V)
- 7** - FN = TO-252AA
- 8** - • None = tube
• TR = tape and reel
• TRL = tape and reel (left oriented)
• TRR = tape and reel (right oriented)
- 9** - Environmental digit:
-M3 = halogen-free, RoHS-compliant and terminations lead (Pb)-free

ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-8CWH02FN-M3	75	3000	Antistatic plastic tube
VS-8CWH02FNTR-M3	2000	2000	13" diameter reel
VS-8CWH02FNTRL-M3	3000	3000	13" diameter reel
VS-8CWH02FNTRR-M3	3000	3000	13" diameter reel

LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?95627
Part marking information	www.vishay.com/doc?95176
Packaging information	www.vishay.com/doc?95033
SPICE model	www.vishay.com/doc?95375

D-PAK (TO-252AA) "M"

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES		SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094			e	2.29 BSC		0.090 BSC		
A1	-	0.13	-	0.005			H	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74 BSC		0.108 REF.		
b3	4.95	5.46	0.195	0.215	3		L2	0.51 BSC		0.020 BSC		
c	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.010") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC® outline TO-252AA

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